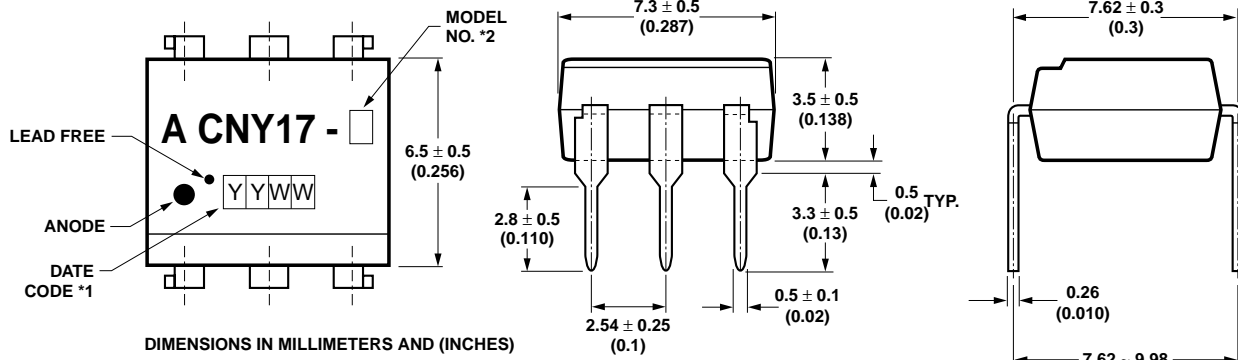
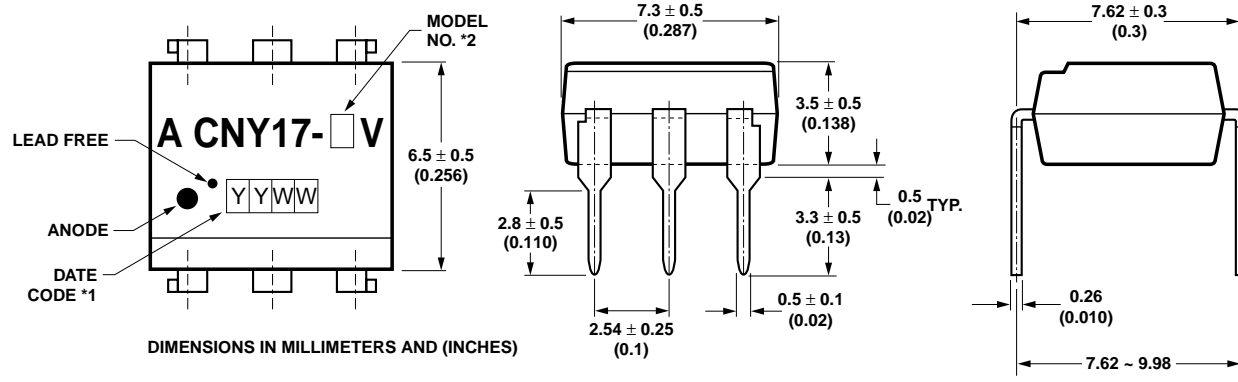


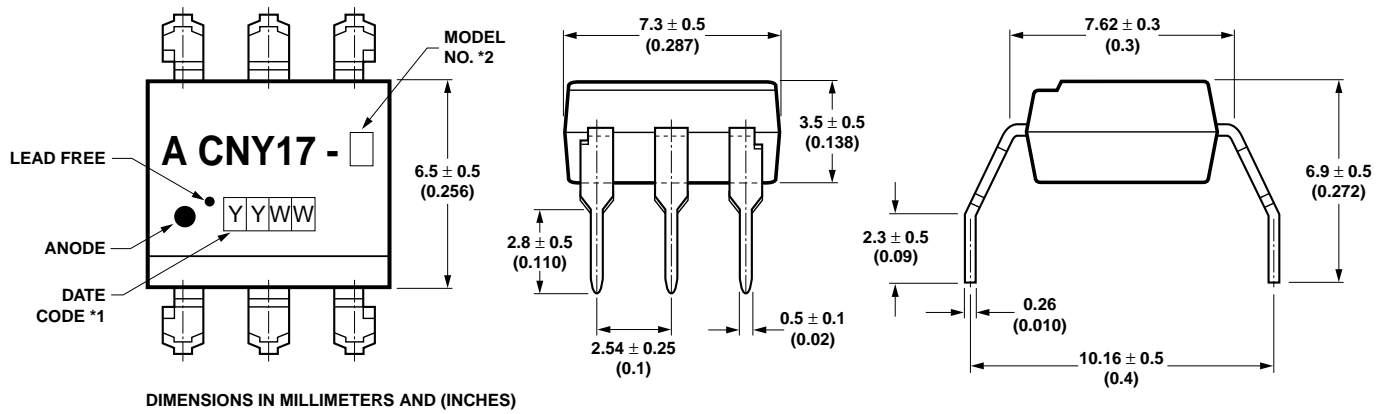
Package Outline Drawings
CNY17-X-000E



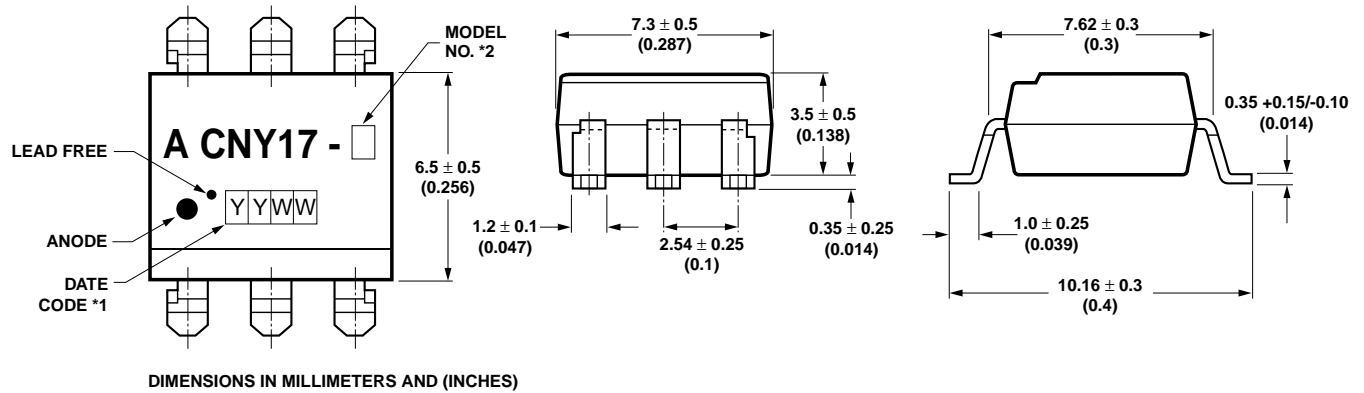
CNY17-X-060E



CNY17-X-W00E

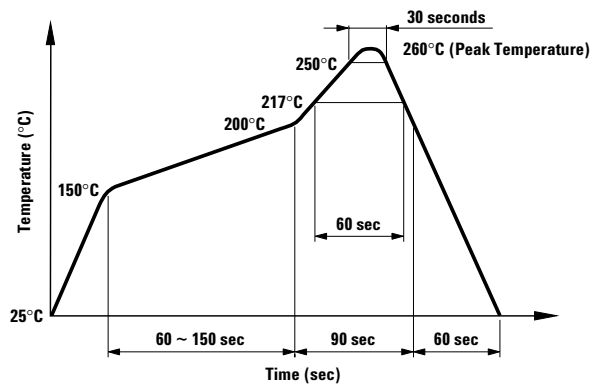


CNY17-X-300E



Solder Reflow Temperature Profile

- 1) One-time soldering reflow is recommended within the condition of temperature and time profile shown at right.
- 2) When using another soldering method such as infrared ray lamp, the temperature may rise partially in the mold of the device. Keep the temperature on the package of the device within the condition of (1) above.



Absolute Maximum Ratings

Storage Temperature, T_S	-55°C to +150°C
Operating Temperature, T_A	-55°C to +100°C
Lead Solder Temperature, max. (1.6 mm below seating plane)	260°C for 10 s
Average Forward Current, I_F	60 mA
Reverse Input Voltage, V_R	6 V
Input Power Dissipation, P_I	100 mW
Collector Current, I_C	150 mA
Collector-Emitter Voltage, V_{CE0}	70 V
Emitter-Collector Voltage, V_{EC0}	6 V
Collector-Base Voltage, V_{CB0}	70 V
Collector Power Dissipation	150 mW
Total Power Dissipation	250 mW
Isolation Voltage, V_{iso} (AC for 1 minute, R.H. = 40 ~ 60%)	5000 Vrms

Electrical Specifications (T_A = 25 °C)

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Forward Voltage	V _F	–	1.4	1.7	V	I _F = 60 mA
Reverse Current	I _R	–	–	10	μA	V _R = 6 V
Terminal Capacitance	C _t	–	–	100	pF	V = 0, f = 1 MHz
Collector Dark Current	I _{CEO}	–	–	50	nA	V _{CE} = 10 V
Collector-Emitter Breakdown Voltage	BV _{CEO}	70	–	–	V	I _C = 0.1 mA, I _F = 0
Emitter-Collector Breakdown Voltage	BV _{ECO}	6	–	–	V	I _E = 10 μA, I _F = 0
Collector-Base Breakdown Voltage	BV _{CBO}	70	–	–	V	I _C = 0.1 mA, I _F = 0
Collector Current	I _C	4	–	32	mA	I _F = 10 mA
*Current Transfer Ratio	CNY17-1 CNY17-2 CNY17-3 CNY17-4	CTR	40 63 100 160	– – – –	80 125 200 320	% V _{CE} = 5 V
Collector-Emitter Saturation Voltage	V _{CE(sat)}	–	–	0.3	V	I _F = 10 mA, I _C = 2.5 mA
Response Time (Rise)	t _r	–	5	10	μs	V _{CE} = 5 V, I _C = 10 mA
Response Time (Fall)	t _f	–	5	10	μs	R _L = 100 Ω
Isolation Resistance	R _{iso}	1 x 10 ¹¹	–	–	Ω	DC 500 V 40 ~ 60% R.H.
Floating Capacitance	C _f	–	–	2	pF	V = 0, f = 1 MHz

* CTR = $\frac{I_C}{I_F} \times 100\%$

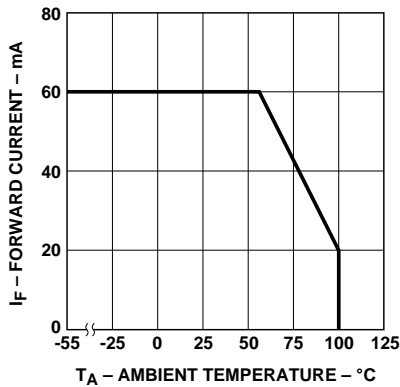


Figure 1. Forward current vs. temperature.

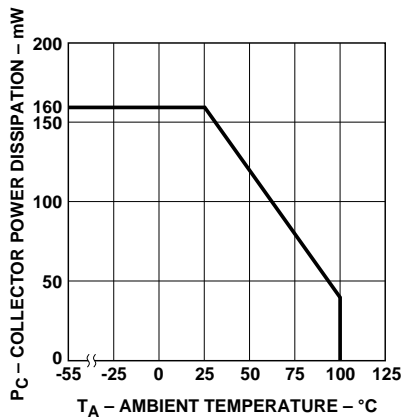


Figure 2. Collector power dissipation vs. temperature.

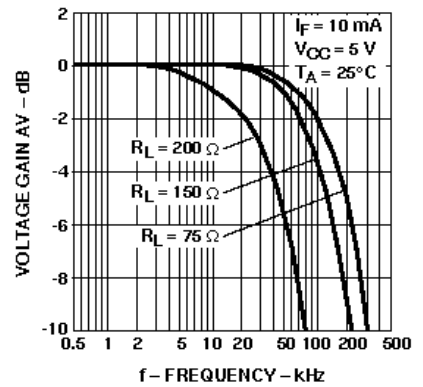


Figure 3. Frequency response.

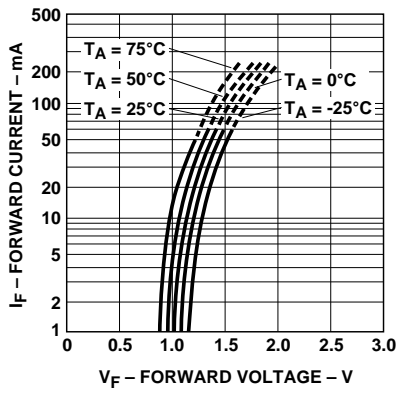


Figure 4. Forward current vs. forward voltage.

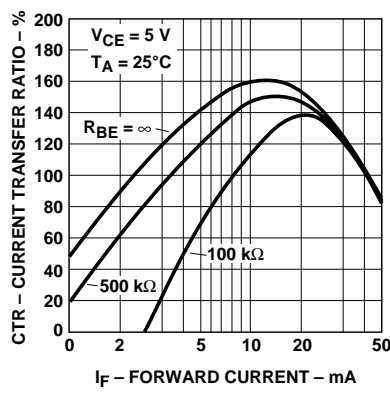


Figure 5. Current transfer ratio vs. forward current.

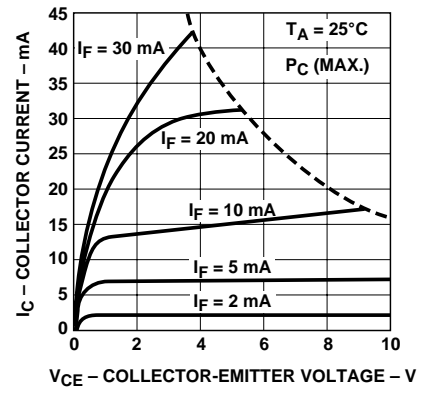


Figure 6. Collector current vs. collector-emitter voltage.

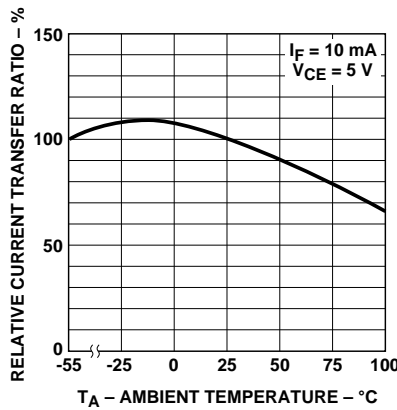


Figure 7. Relative current transfer ratio vs. temperature.

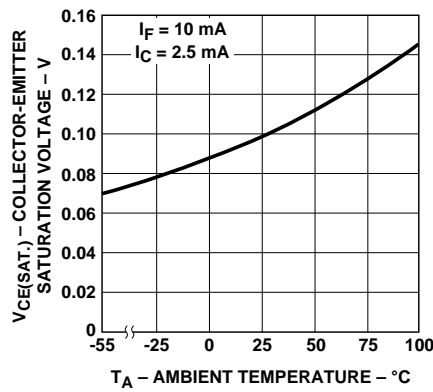


Figure 8. Collector-emitter saturation voltage vs. temperature.

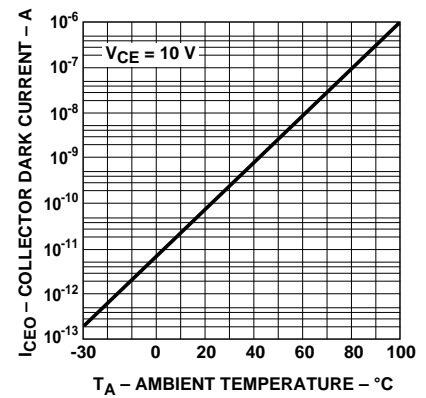


Figure 9. Collector dark current vs. temperature.

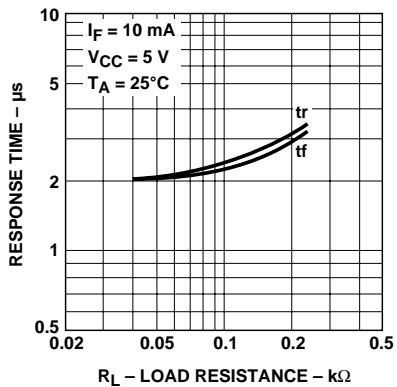


Figure 10. Response time vs. load resistance.

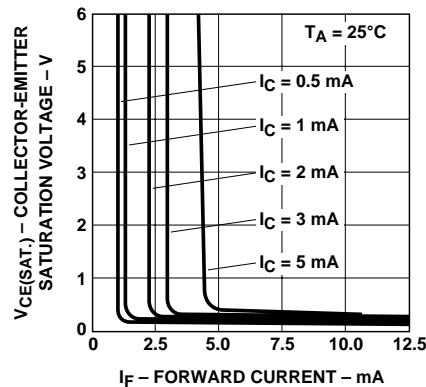
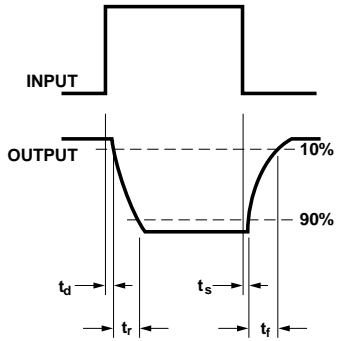
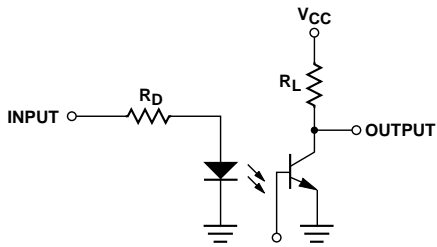
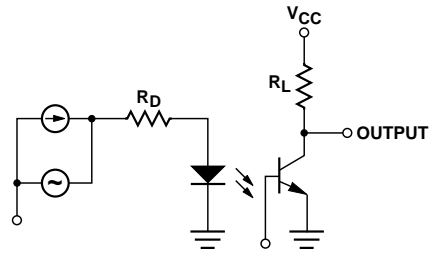


Figure 11. Collector-emitter saturation voltage vs. forward current.

Test Circuit for Response Time



Test Circuit for Frequency Response



www.agilent.com/semiconductors

For product information and a complete list of distributors, please go to our web site.

For technical assistance call:

Americas/Canada: +1 (800) 235-0312 or (916) 788-6763

Europe: +49 (0) 6441 92460

China: 10800 650 0017

Hong Kong: (+65) 6756 2394

India, Australia, New Zealand: (+65) 6755 1939

Japan: (+81 3) 3335-8152 (Domestic/International), or 0120-61-1280 (Domestic Only)

Korea: (+65) 6755 1989

Singapore, Malaysia, Vietnam, Thailand, Philippines, Indonesia: (+65) 6755 2044

Taiwan: (+65) 6755 1843

Data subject to change.

Copyright © 2004 Agilent Technologies, Inc.

Obsoletes 5989-0290EN

October 27, 2004

5989-1736EN